

NOTES:

1) MATERIAL:

HOUSING: GLASS FILLED NYLON, UL94V-0, COLOR: BLACK
INSULATOR: GLASS FILLED NYLON, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE: .012/ 0.30 THICK

2) FINISH:

TERMINALS:

SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/ 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/ 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/ 1.27 MICROMETERS MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAIL AREA.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43223-001.

4) PACKAGING SPECIFICATION:

UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TRAYS PER MOLEX
PACKAGING SPECIFICATION PK-43249-004.

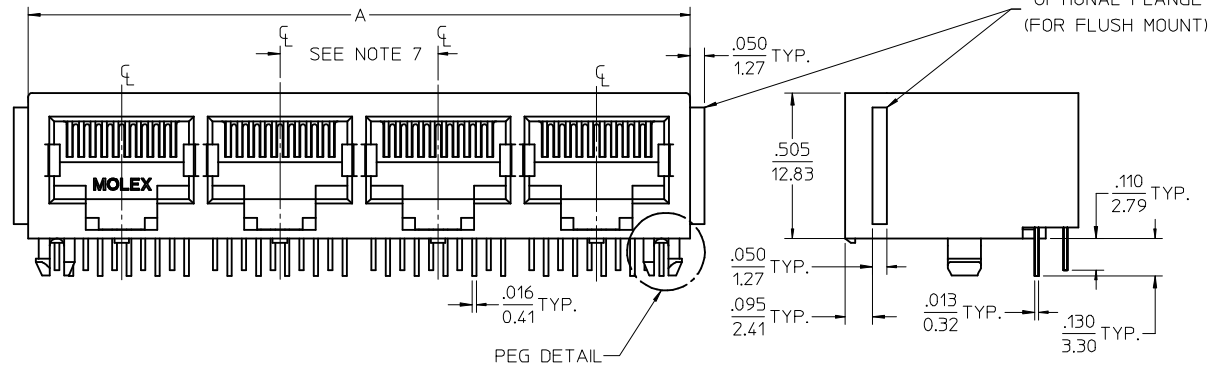
5) SEE SHEETS 4-6 FOR P.C. BOARD LAYOUTS.

6) SEE SHEET 2 FOR THE SHIELDED JACK ASSEMBLY.

7) FOR 6 CIRCUIT JACKS CENTERLINE TO CENTERLINE SPACING IS .448/ 11.38, FOR 8 CIRCUIT JACKS CENTERLINE TO CENTERLINE SPACING IS .550/ 13.97.

8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

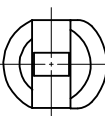
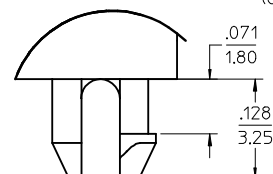
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



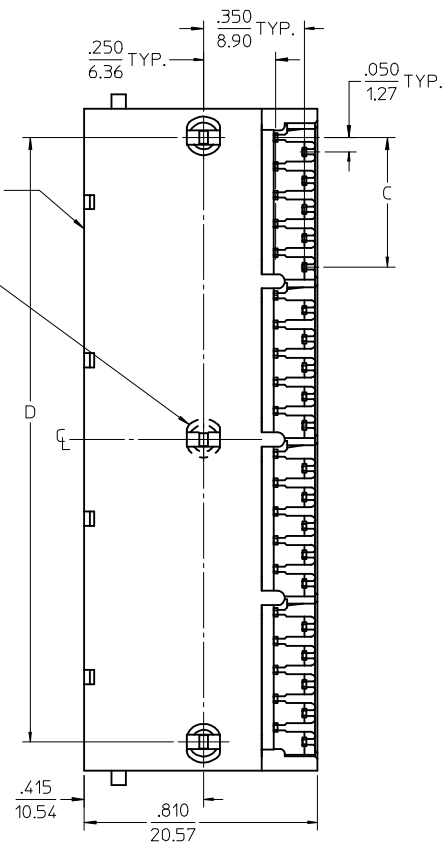
4 PORT 8 LOADED
10 JACK SHOWN

UNSHIELDED GANGED JACK ASSEMBLY
SEE SHEET 3

CENTER PEG
(8 PORT ASSY. ONLY)



SNAP-FIT
PEG DETAIL
SCALE 8:1



6 CIRCUIT HOUSING

CIRCUIT SIZE	NO. OF PORTS	DIM. A	DIM. C	DIM. D
6	2	.985 (25.02)	.250 (6.35)	.848 (21.54)
4	2	.985 (25.02)	.150 (3.81)	.848 (21.54)
2	2	.985 (25.02)	.050 (1.27)	.848 (21.54)
6	3	1.433 (36.40)	.250 (6.35)	1.296 (32.92)
4	3	1.433 (36.40)	.150 (3.81)	1.296 (32.92)
2	3	1.433 (36.40)	.050 (1.27)	1.296 (32.92)
6	4	1.881 (47.78)	.250 (6.35)	1.744 (44.30)
4	4	1.881 (47.78)	.150 (3.81)	1.744 (44.30)
2	4	1.881 (47.78)	.050 (1.27)	1.744 (44.30)
6	5	2.329 (59.16)	.250 (6.35)	2.192 (55.68)
4	5	2.329 (59.16)	.150 (3.81)	2.192 (55.68)
2	5	2.329 (59.16)	.050 (1.27)	2.192 (55.68)
6	6	2.777 (70.54)	.250 (6.35)	2.640 (67.06)
4	6	2.777 (70.54)	.150 (3.81)	2.640 (67.06)
2	6	2.777 (70.54)	.050 (1.27)	2.640 (67.06)
6	8	3.673 (93.29)	.250 (6.35)	3.536 (89.81)
4	8	3.673 (93.29)	.150 (3.81)	3.536 (89.81)
2	8	3.673 (93.29)	.050 (1.27)	3.536 (89.81)

8 CIRCUIT HOUSING

CIRCUIT SIZE	NO. OF PORTS	DIM. A	DIM. C	DIM. D
10	2	1.200 (30.48)	.450 (11.43)	1.000 (25.40)
8	2	1.200 (30.48)	.350 (8.89)	1.000 (25.40)
6	2	1.200 (30.48)	.250 (6.35)	1.000 (25.40)
10	3	1.750 (44.45)	.450 (11.43)	1.550 (39.37)
8	3	1.750 (44.45)	.350 (8.89)	1.550 (39.37)
6	3	1.750 (44.45)	.250 (6.35)	1.550 (39.37)
4	3	1.750 (44.45)	.150 (3.81)	1.550 (39.37)
10	4	2.300 (58.42)	.450 (11.43)	2.100 (53.34)
8	4	2.300 (58.42)	.350 (8.89)	2.100 (53.34)
4	4	2.300 (58.42)	.150 (3.81)	2.100 (53.34)
4	5	2.850 (72.39)	.150 (3.81)	2.650 (67.31)
10	5	2.850 (72.39)	.450 (11.43)	2.650 (67.31)
8	5	2.850 (72.39)	.350 (8.89)	2.650 (67.31)
10	6	3.400 (86.36)	.450 (11.43)	3.200 (81.28)
8	6	3.400 (86.36)	.350 (8.89)	3.200 (81.28)
10	8	4.500 (114.30)	.450 (11.43)	4.300 (109.22)
8	8	4.500 (114.30)	.350 (8.89)	4.300 (109.22)

ADD BLOCK TOL
EC NO: UCP2009-0477
DRWN: BELL
CHKD: BELL
APPR: FSMITH

2008/09/05
2008/09/11
2008/09/11

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .005	± .0005
3 PLACES	± .005	± .0005
2 PLACES	± 0.038	± .0015
1 PLACE	± .005	± .0005

ANGULAR ± 1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY
JTR

DATE
1993/10/18

CHECKED BY
JTR

DATE
1993/10/18

APPROVED BY
RAS

DATE
1993/10/18

MATERIAL NO.
SEE SHTS 3

SIZE
C

SCALE
3:1

DESIGN UNITS
INCH

THIRD ANGLE PROJECTION

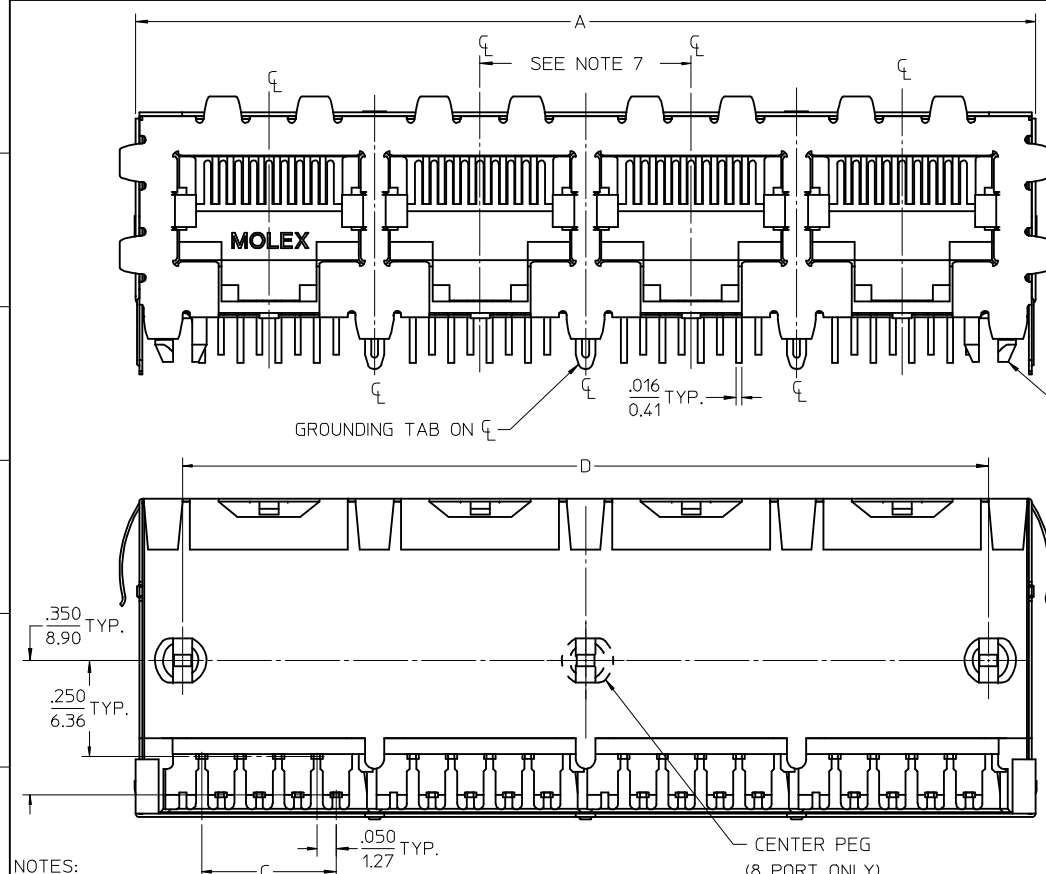
LOW PROFILE GANGED,
RIGHT ANGLE MODULAR JACK
ASSEMBLY

MOLEX INCORPORATED

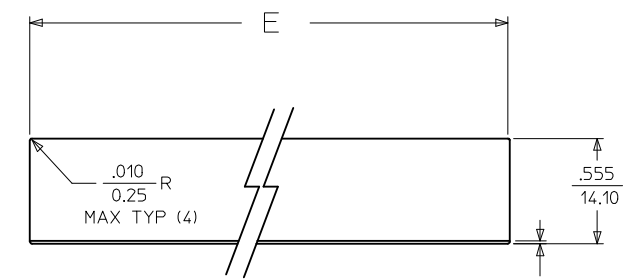
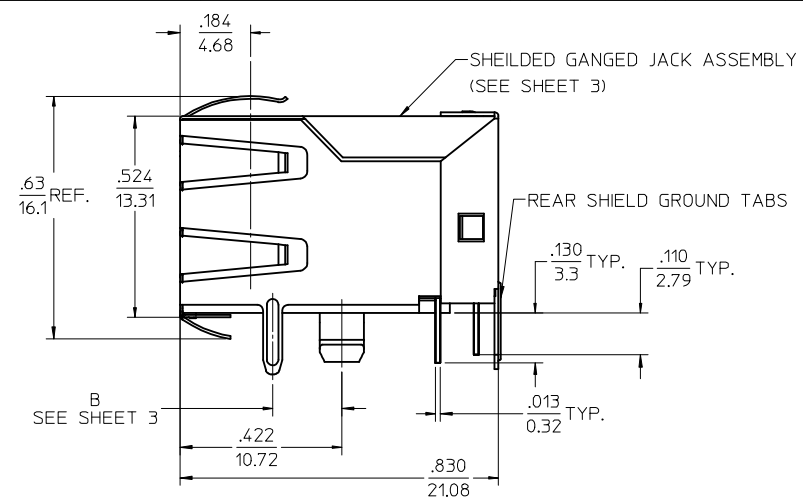
DOCUMENT NO.
SDA-43223

SHEET NO.
1 OF 6

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

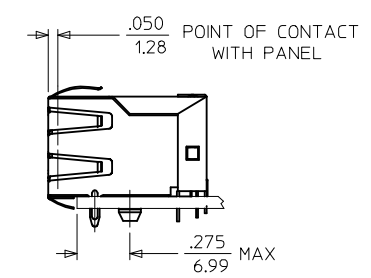


- NOTES:
- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, UL94V-0, COLOR: BLACK
INSULATOR: GLASS FILLED NYLON, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE: .012/ 0.30 THICK
SHIELD: BRASS, FRONT .007/ 0.18 THICK, REAR .010/ 0.25 THICK
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/ 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/ 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/ 1.27 MICROMETERS MIN.
SHIELD:
*100 MICROINCHES/ 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES/ 1.27 MICROMETERS COPPER UNDERPLATE. PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAIL AND/OR SHIELD.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43223-001.
 - 4) PACKAGING SPECIFICATION:
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44150-004.
 - 5) SEE SHEETS 4-6 FOR P.C. BOARD LAYOUTS.
 - 6) REAR SHIELD IS AVAILABLE WITH (1) CENTERED GROUND TAB ON 4 & 8 PORT VERSIONS.
 - 7) 8 CIRCUIT JACKS CENTERLINE TO CENTERLINE SPACING IS .550/ 13.97.
 - 8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



SUGGESTED PANEL OPENING

SCALE : 2/1

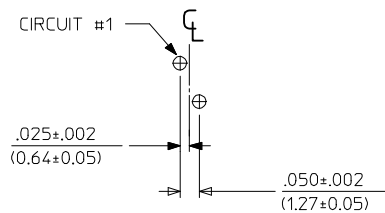


4 PORT 8 LOADED
8 JACK SHOWN

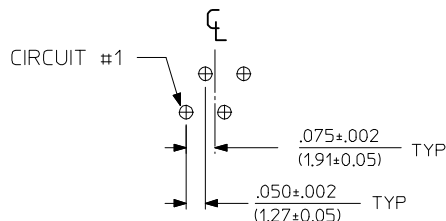
HOUSING SIZE	CIRCUIT SIZE	NO. OF PORTS	DIM. A	DIM. C	DIM. D	DIM. E
8	8	2	1.224 (31.09)	.350 (8.89)	1.000 (25.40)	1.255 (31.88)
8	8	4	2.324 (59.03)	.350 (8.89)	2.100 (53.34)	2.355 (59.82)
8	8	6	3.424 (86.97)	.350 (8.89)	3.200 (81.28)	3.455 (87.76)
8	8	8	4.524 (114.91)	.350 (8.89)	4.300 (109.22)	4.555 (115.97)
8	2	8	4.524 (114.91)	.050 (1.27)	4.300 (109.22)	4.555 (115.97)

SEE SHEET 1 EC NO: UCP2009-0477 DRWN:JBELL CHKD:JBELL APPR:FSM/TH 2008/09/05 2008/09/11 2008/09/11	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		mm INCH		DRAWN BY JTR	DATE 1993/10/18	LOW PROFILE GANGED, RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX INCORPORATED		
		4 PLACES ± --- ± ---		CHECKED BY JTR	DATE 1993/10/18			
		3 PLACES ± --- ± .015		APPROVED BY RAS	DATE 1993/10/18			
2 PLACES ± 0.38 ± ---		ANGULAR ± 1/2°		MATERIAL NO. SEE SHTS 3		DOCUMENT NO. SDA-43223	SHEET NO. 2 OF 6	
1 PLACE ± --- ± ---		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

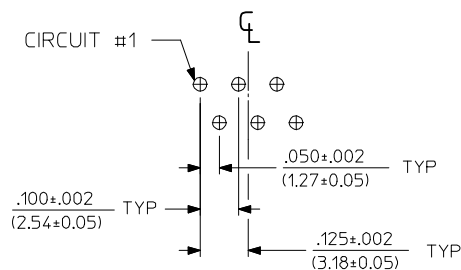
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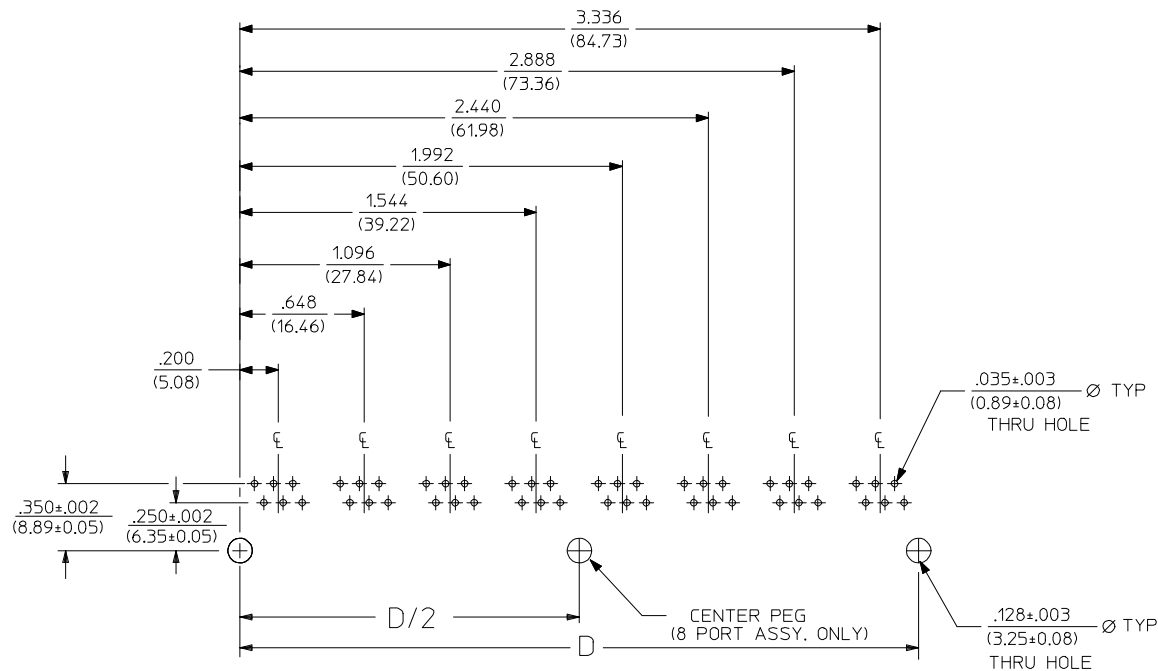
6 LOADED 2 DETAIL
SCALE: 4/1



6 LOADED 4 DETAIL
SCALE: 4/1



6 LOADED 6 DETAIL
SCALE: 4/1

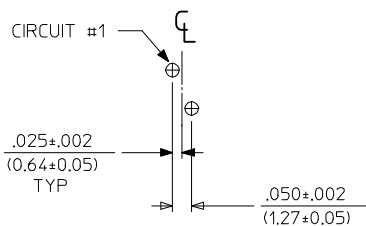


SUGGESTED P.C. BOARD LAYOUT
COMPONENT SIDE OF BOARD
8 PORT, 6 LOADED 6, LAYOUT SHOWN
(SNAP-FIT VERSIONS)

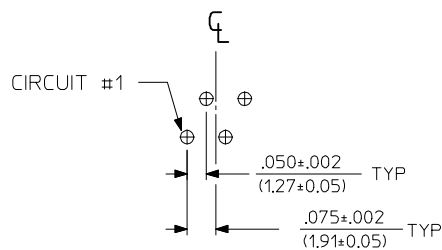
NOTES:
1. RECOMMENDED PCB THICKNESS .062±.005/(1.57±0.13)

NUMBER OF PORTS	DIM. D
2	.848 (21.54)
3	1.296 (32.92)
4	1.744 (44.30)
5	2.192 (55.68)
6	2.640 (67.06)
8	3.536 (89.81)

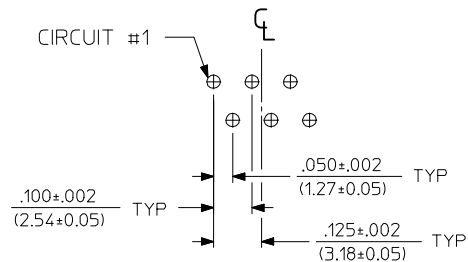
SEE SHEET 1 EC NO: UCP2009-0477 DRWN:JBELL 2008/09/05 CHKD:JBELL 2008/09/11 APPR:FSMTH 2008/09/11 K1	DESCRIPTION	REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 2:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION		
					mm	INCH	DRAWN BY JTR	DATE 1993/10/18	TITLE LOW PROFILE GANGED, RIGHT ANGLE MODULAR JACK ASSEMBLY			
				4 PLACES ± ---	± ---	CHECKED BY	DATE 1993/10/18	APPROVED BY			DATE 1993/10/18	 MOLEX INCORPORATED
				3 PLACES ± ---	± .015	MATERIAL NO.		DOCUMENT NO.			SHEET NO. 4 OF 6	
				2 PLACES ± 0.38	± ---	SEE SHT 3		SDA-43223				
				1 PLACE ± ---	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
				ANGULAR ±1/2°								
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



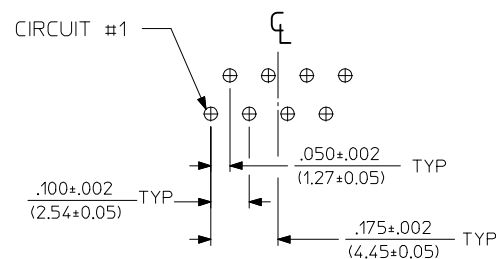
8 LOADED 2 DETAIL
SCALE: 4/1



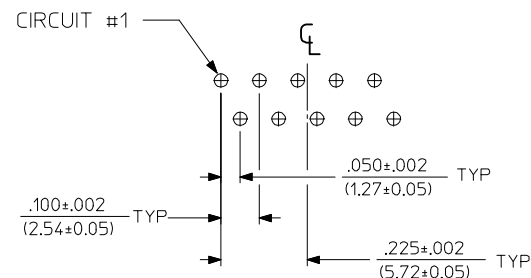
8 LOADED 4 DETAIL
SCALE: 4/1



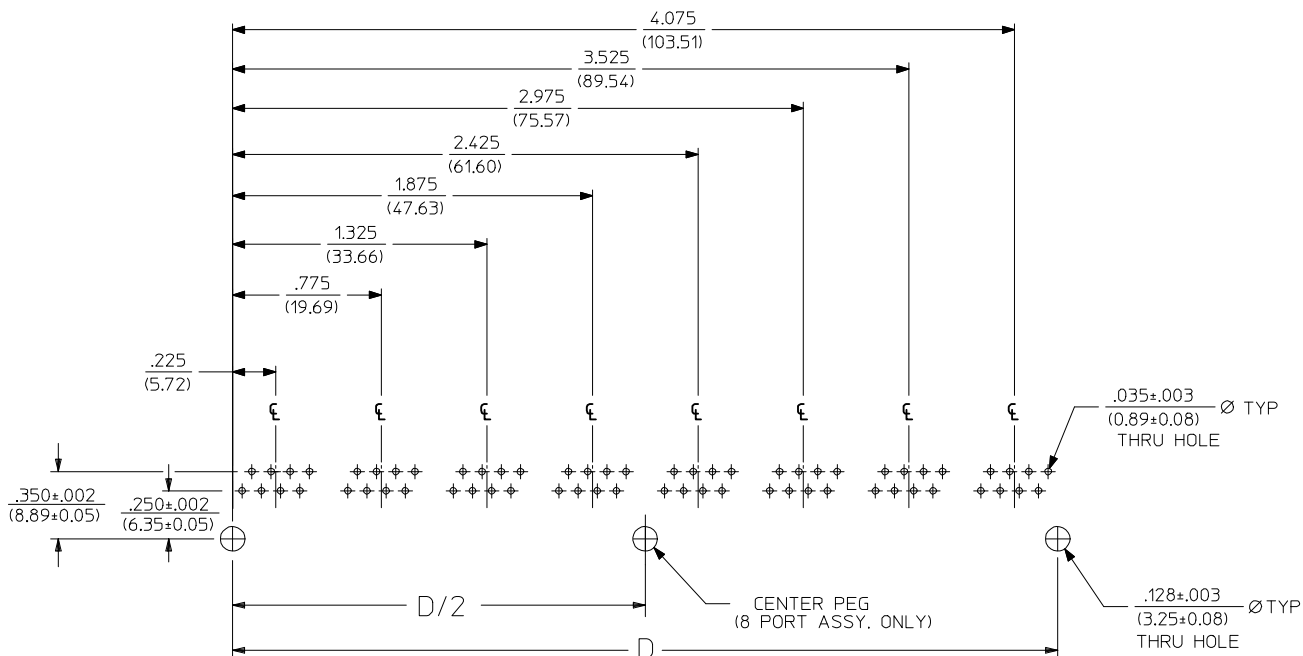
8 LOADED 6 DETAIL
SCALE: 4/1



8 LOADED 8 DETAIL
SCALE: 4/1



8 LOADED 10 DETAIL
SCALE: 4/1



SUGGESTED P.C. BOARD LAYOUT
COMPONENT SIDE OF BOARD
8 PORT, 8 LOADED 8
(SNAP-FIT VERSIONS)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

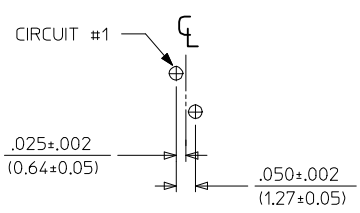
NUMBER OF PORTS	DIM. D
2	1.000 (25.40)
3	1.550 (39.37)
4	2.100 (53.34)
5	2.650 (67.31)
6	3.200 (81.28)
8	4.300 (109.32)

SEE SHEET 1	EC NO: UCP2009-0477	2008/09/05	DRWN:JBELL	2008/09/11	CHKD:JBELL	2008/09/11	APPR:FSM/TH	2008/09/11
K1	REV	DESCRIPTION	QUALITY SYMBOLS	▽=0	▽=0			

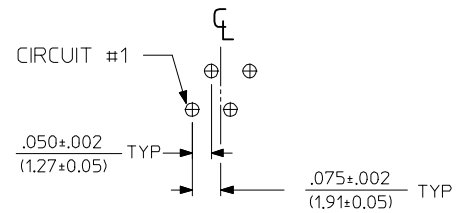
GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± .015
2 PLACES ± 0.38	± ---
1 PLACE ± ---	± ---
ANGULAR ± 1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE IN/MM	
DRAWN BY	DATE
JTR	1993/10/18
CHECKED BY	DATE
JTR	1993/10/18
APPROVED BY	DATE
RAS	1993/10/18
MATERIAL NO.	DOCUMENT NO.
SEE SHT 3	SDA-43223
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
C	

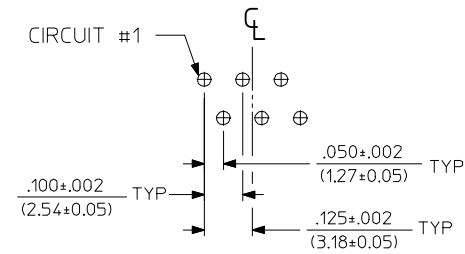
SCALE 2:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
TITLE		
LOW PROFILE GANGED, RIGHT ANGLE MODULAR JACK ASSEMBLY		
MOLEX INCORPORATED		
SHEET NO. 5 OF 6		



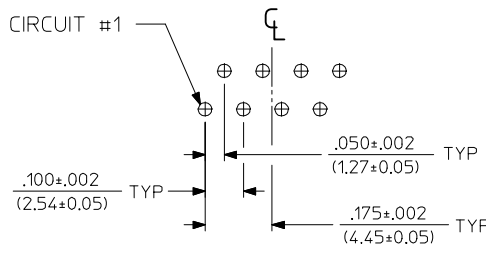
8 LOADED 2 DETAIL
SCALE: 4/1



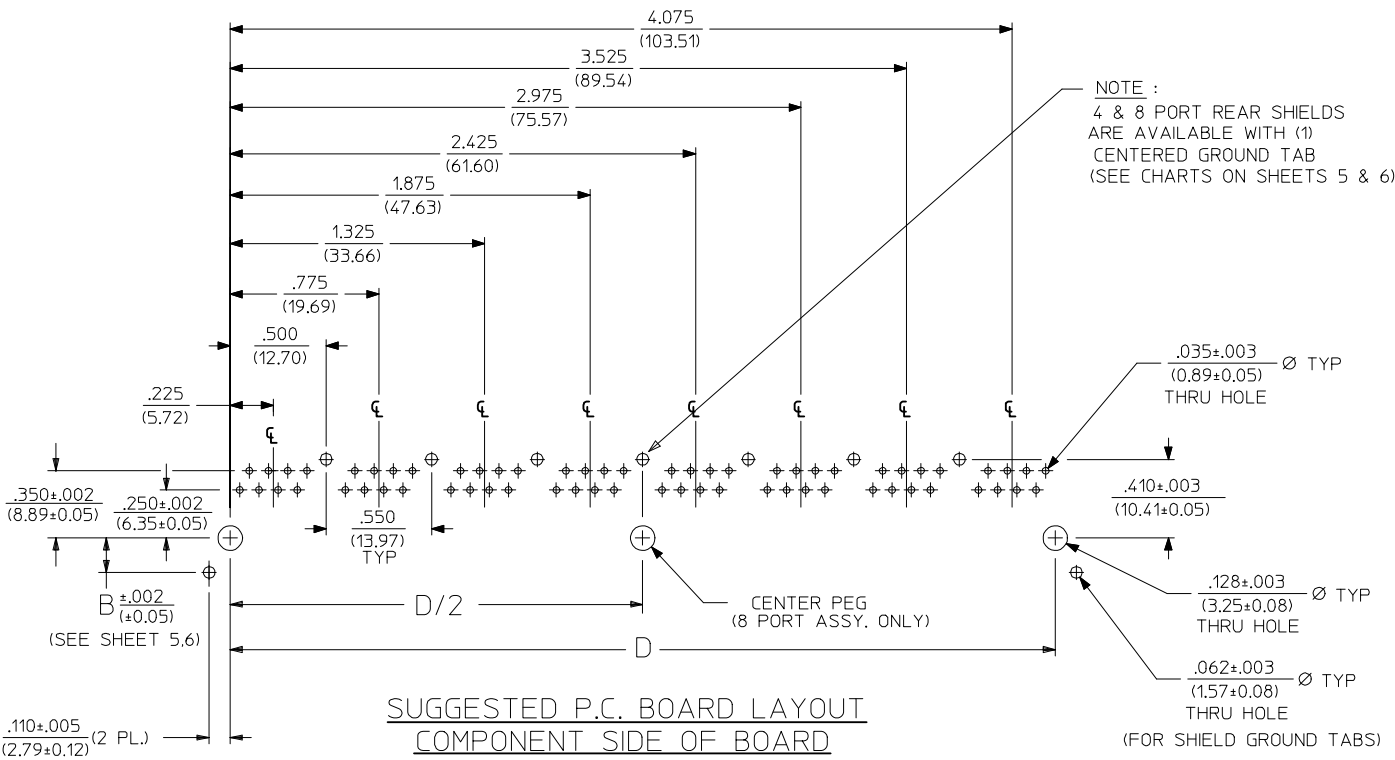
8 LOADED 4 DETAIL
SCALE: 4/1



8 LOADED 6 DETAIL
SCALE: 4/1



8 LOADED 8 DETAIL
SCALE: 4/1



NOTE :
4 & 8 PORT REAR SHIELDS
ARE AVAILABLE WITH (1)
CENTERED GROUND TAB
(SEE CHARTS ON SHEETS 5 & 6)

SUGGESTED P.C. BOARD LAYOUT
COMPONENT SIDE OF BOARD
8 PORT, 8 LOADED 8
(SHIELDED) LAYOUT SHOWN
(SNAP-FIT VERSIONS)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

NUMBER OF PORTS	DIM. D
2	1.000 (25.40)
4	2.100 (53.34)
6	3.200 (81.28)
8	4.300 (109.32)

SEE SHEET 1	EC NO: UCP2009-0477	2008/09/05
	DRWN:JBELL	2008/09/11
	CHKD:JBELL	2008/09/11
	APPR:FSM/TH	2008/09/11
REV	DESCRIPTION	
K1		

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
▽=0	
▽=0	
	ANGULAR ±1/2°
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS
IN/MM	2:1	INCH
DRAWN BY	DATE	
JTR	1993/10/18	
CHECKED BY	DATE	
JTR	1993/10/18	
APPROVED BY	DATE	
RAS	1993/10/18	
MATERIAL NO.		
SEE SHT 3		
SIZE		

TITLE	THIRD ANGLE PROJECTION
LOW PROFILE GANGED, RIGHT ANGLE MODULAR JACK ASSEMBLY	
MOLEX INCORPORATED	
DOCUMENT NO. SDA-43223	SHEET NO. 6 OF 6
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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www.lifeelectronics.ru